

ABSTRACT OF THE DISCLOSURE

A tape ball grid array package and a method of fabricating the package. A dielectric tape having a metallic layer on both sides is provided. The metallic layers are patterned to form circuits. A plurality of via holes is formed in the dielectric tape. The via holes pass
5 through the lower metallic layer and the tape dielectric but stop at the upper metallic layer, thereby forming a plurality of blind holes. A solder mask layer is formed over each side of the tape and the solder mask layers are patterned to expose a portion of the metallic layer serving as contact points for connecting with a chip. A solder ball is inserted into each blind
10 hole. One end of the solder ball protrudes from the surface of the solder mask layer. Wire-bonding operation or flip-chip assembly process is conducted to form electrical connection between the chip and the contact points.